# Kulicke & Soffa Launches FCC™ Hub Blades - A Customizable Wafer Dicing Solution for Advanced Packaging

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment, today announced the formal launch of its new FCC™ Hub Blades, extending the successful AccuPlus™ series. The new FCC™ Hub Blades offer a customizable solution for flip chip, wafer level packaging (WLP) and thick wafer dicing with improved efficiency and cost of ownership.

The advanced packaging market, flip chip and WLP wafer dicing demand has increased exponentially. These advanced packaging technologies further enable package size reductions for the most advanced processor and memory devices serving the latest smart phone and tablet segments which generally requires high accuracy and dicing consistency. K&S FCC™ Hub Blades are designed to fulfill the growing process requirement.

Albert Yue, Senior Manager of the Blades Business Line, said, "By optimizing key blade elements such as diamond grit size, concentration and nickel bond hardness, in conjunction with the newly introduced features, the FCC™ Hub Blades deliver superior cut quality and useful life to drive accuracy requirement and reduce cost of ownership.

Features:

- Supreme Straight Cut control for useful life
- Improve cutting power for thick wafer dicing
- Enable high-feed rate special pre-cut recipe to improve initial slant cut

FCC™ is a special feature under AccuPlus™ series which consist of both Discrete series designed for enabling high cutting power and Ultra series bond hardness for high loading processes (Metalized saw street and backside coated wafers).

Diamond concentration is a critical factor for blade cutting power. Lower concentrations provide greater resistance to blade loading, and higher concentrations enable higher feed rates and longer blade life. K&S FCC™ Hub Blades are available in six different diamond concentrations to achieve the desired equilibrium among loading, blade life and throughput.

Chan Pin Chong, Kulicke & Soffa's Vice President for Wedge Bonders, Capillaries and Blades Business Lines, said, "K&S has a rich history of delivering R&D advances that help customers improve the semiconductor manufacturing of the advanced packaging product, we believe that they will continue to benefit from our innovative offering of products and solutions. With cost and yield continuing to be chief production concerns, customers can reduce die chipping and cracks to help reduce expenses while improving their operational efficiency and overall end product quality."

The FCC™ Hub Blades will debut at the SEMICON China show at the Shanghai New International Expo Centre, Hall N5, Booth #5331, from March 15-17, 2016.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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